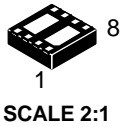


MECHANICAL CASE OUTLINE

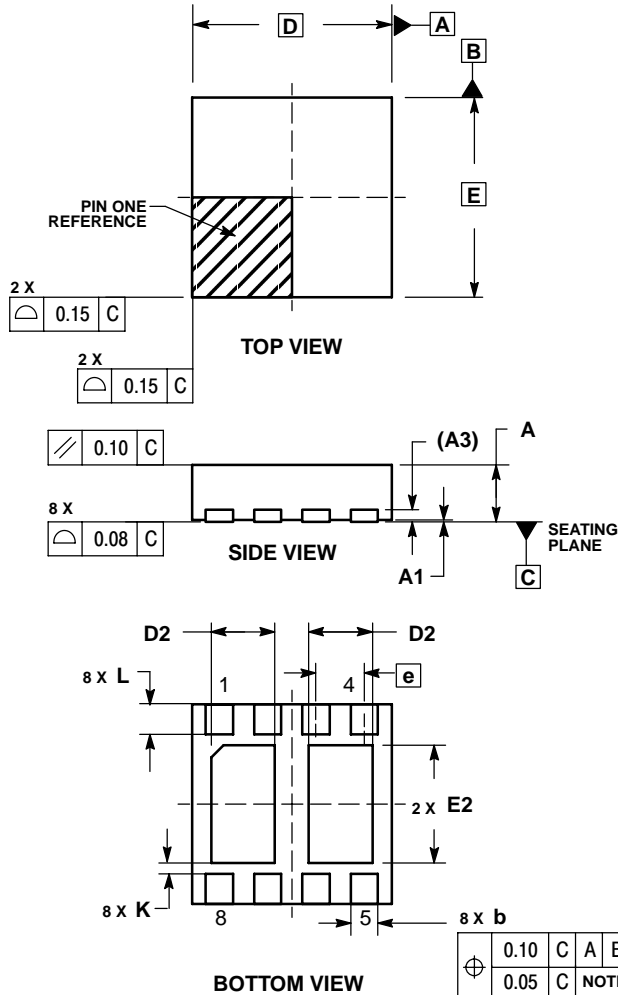
PACKAGE DIMENSIONS

ON Semiconductor®



DFN8
CASE 506AL-01
ISSUE A

DATE 20 DEC 2005

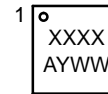


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.35	0.40	0.45
D	3.30 BSC		
D2	0.95	1.05	1.15
E	3.30 BSC		
E2	1.80	1.90	2.00
e	0.80 BSC		
K	0.21	---	---
L	0.30	0.40	0.50

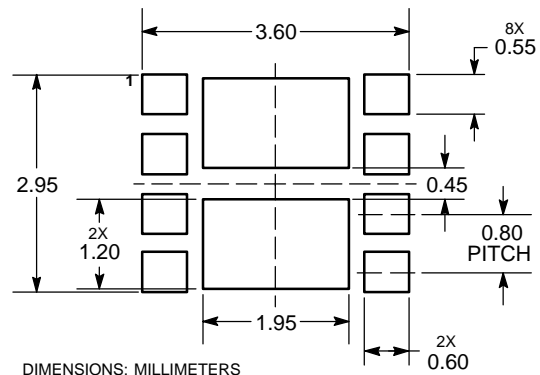
GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- STYLE 1:
PIN 1. IN
2. GND
3. CNTRL
4. DRAIN
5. SOURCE
6. GATE
7. OUT
8. VCC

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN8, 3.3X3.3 MM, 0.8 MM PITCH, DUAL FLAG	PAGE 1 OF 2

